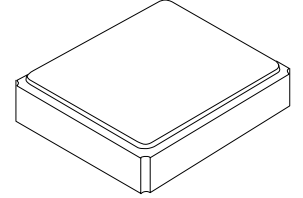


**XTL2119P**

**40.000000 MHz  
Crystal Unit**



**SM3225-4**

## Features:

- Surface Mount Hermetic Package
- Excellent Reliability Performance
- Good Frequency Perturbation and Stability over temperature
- Ultra Miniature Package
- Moisture Sensitivity Level: 1

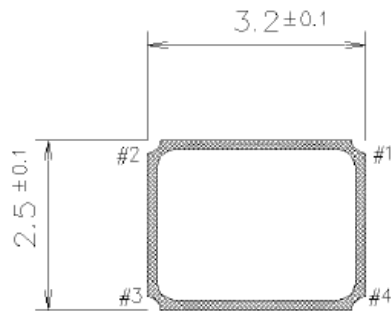
## Description and Applications:

Surface mount 3.2 mm x 2.5 mm crystal unit for customer for use in wireless communications devices, especially for a need of ultra miniature package for mobility.

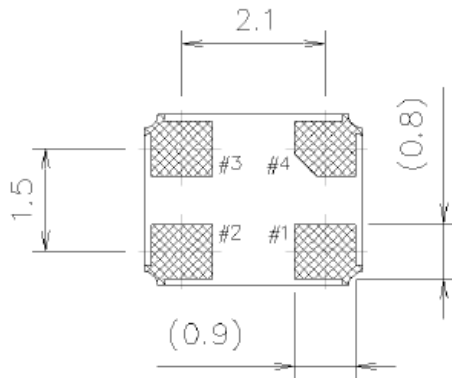
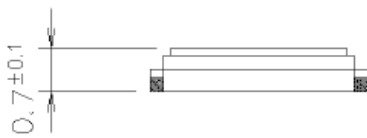
## Electrical Specifications:

<b>XTL2119P</b>	<b>Specification</b>
Nominal Frequency	40.000000 MHz
Mode of Oscillation	Fundamental
Storage Temperature Range	-40°C to +125°C
Operating Temperature Range	-40°C to +105°C
Frequency Stability over Operating Temperature	-40°C to +100°C +/- 15 ppm (referred to the value at 25°C) +100°C to +105°C +/- 20 ppm (referred to the value at 25°C)
Frequency Make Tolerance (FL)	+/- 7 ppm @ 25°C +/- 3°C
Equivalent Series Resistance (ESR)	15 Ω max.
Nominal Drive Level	10 uW and 400uW max
Shunt Capacitance (Co)	3.0 pF max
Load Capacitance (CL)	10 pF
Trim Sensitivity (TS)	10~13 ppm/pf
Aging	+/-2ppm/year
Insulation Resistance	500 MΩ min./DC 100V
Unit Weight	0.017+/-0.005 g

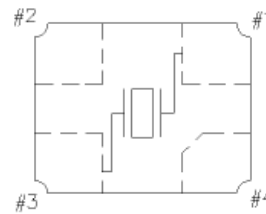
## Mechanical Dimensions (mm):



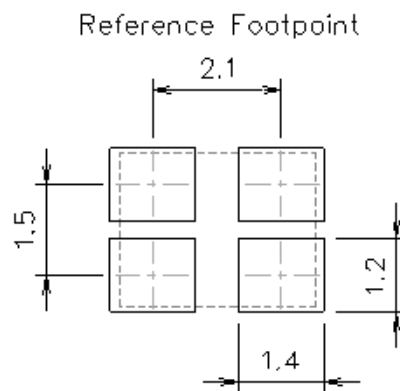
	Pin Connection
#1 pin	IN/OUT
#2 pin	GND
#3 pin	IN/OUT
#4 pin	GND



Internal Connections  
(Top View)

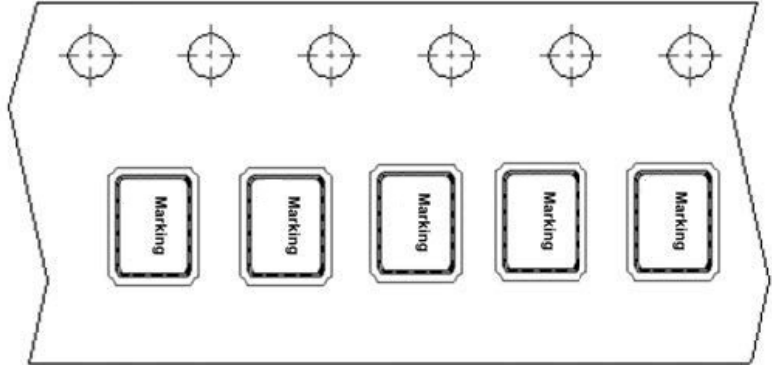


## Recommended Land Pattern: (unit: mm)



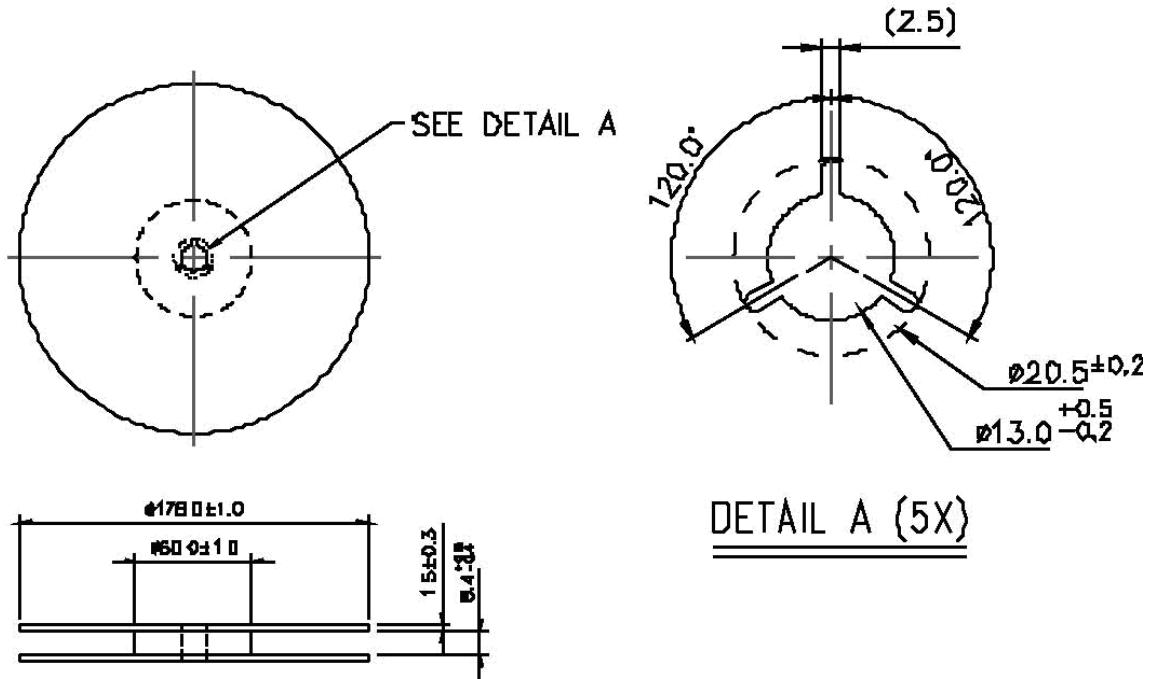
# Marking:

Y = Year, WW = Week, S = Shift

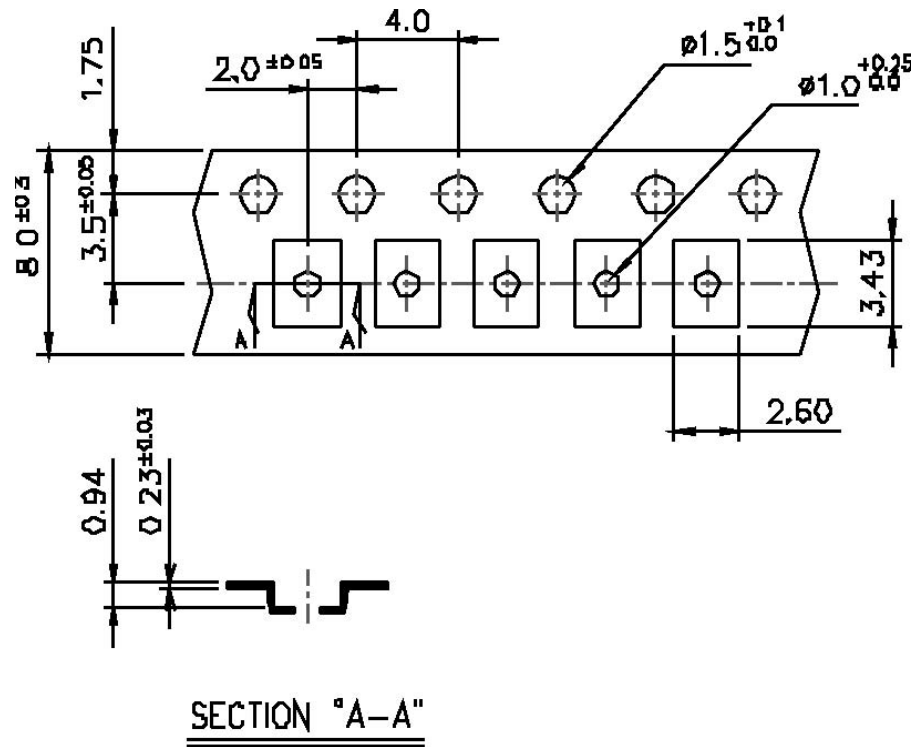


# Reel Dimensions (mm):

Reel Count:  
7' = 3000



Tape Dimensions (mm):

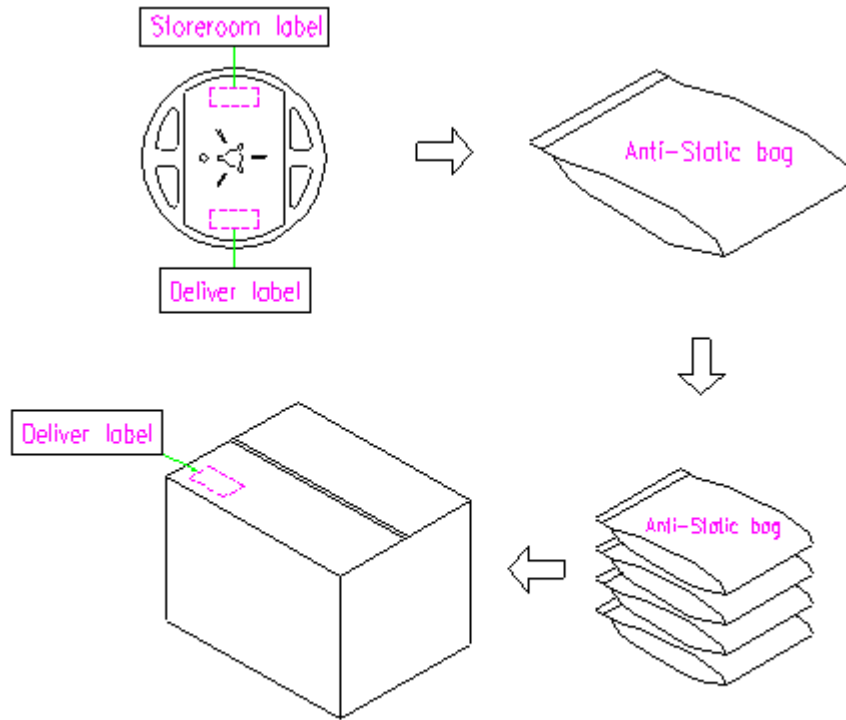


[NOTE]

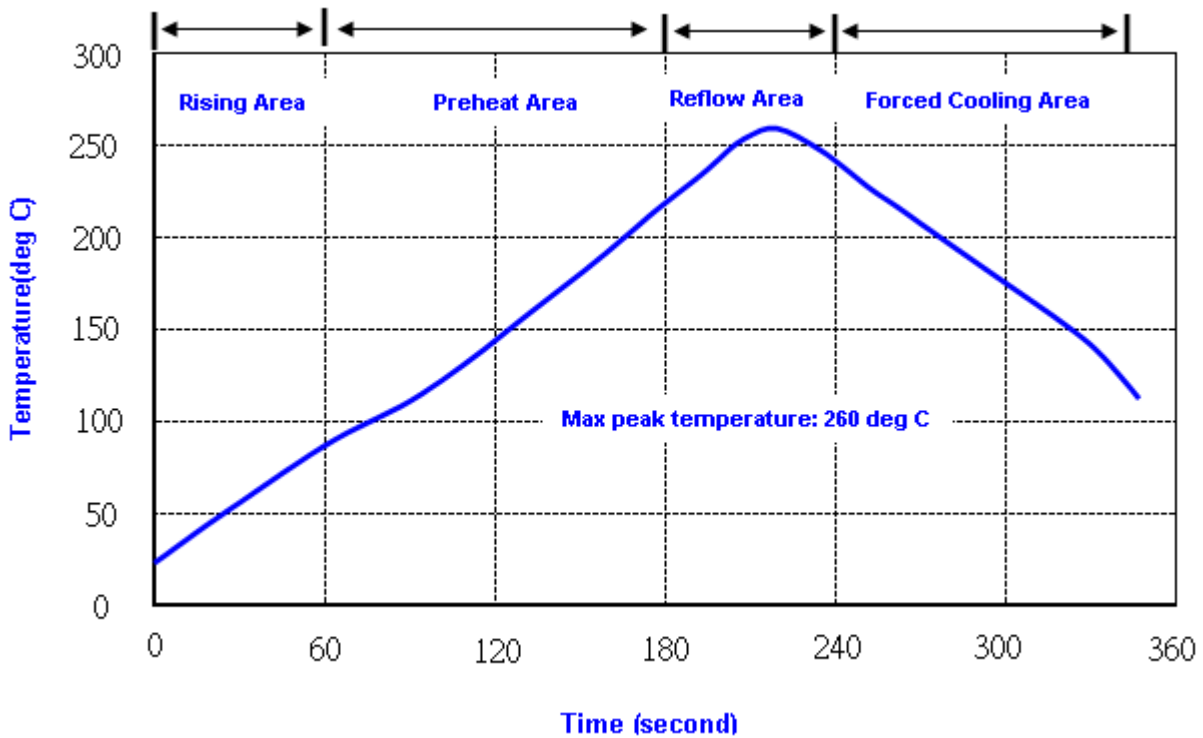
- 1 UNIT : mm.
- 2 UNLESS OTHERWISE SPECIFIED TOLERANCE ON DIM.  $\pm 0.1$ mm.
- 3 MATERIAL : CONDUCTIVE POLYSTYRENE.
- 4 COLOR : BLACK.
- 5 10 PITCHES CUMULATIVE TOLERANCE  $\pm 0.2$ mm.

# Packing Quantity/Packing:

3K pcs maximum per reel



## Reflow Profile:



**Note: 1. Max peak temperature: 260+/-5 deg C; Time: 10+/-2 sec**

**2. Temperature: 217+/-5 deg C; Time: 90~100 sec**

# Reliability Specifications

Test name	Test process / method	Reference standard
<b>Mechanical characteristics</b>		
resistance to Soldering heat (IR reflow)	Temp./ Duration : 265°C /10sec ×2 times Total time : 4min.(IR-reflow)	EIAJED-4701 -300(301)M(II)
Vibration	Total peak amplitude : 1.5mm Vibration frequency : 10 to 2000 Hz : Sweep period : 20 minute Vibration directions : 3 mutually perpendicular Duration : 2 hr / direc.	MIL-STD 202G method 204
Mechanical Shock	directions : 3 impacts per axis Acceleration : 3000g's, +20/-0 % Duration : 0.3 ms (total 18 shocks) Waveform : Half-sine	MIL-STD 202G method 213
Solderability	Solder Temperature:265±5°C Duration time: 5±0.5 seconds.	J-STD 202G method 213
<b>Environmental characteristics</b>		
Thermal Shock	Heat cycle conditions -40 °C (30min) ↔ 85°C (30min) * cycle time : 10 times	MIL-STD 883G method 1010.8
Humidity test	Temperature : 85 ± 2 °C Relative humidity : 85% Duration : 96 hours	MIL-STD 202G method 103
Dry heat ( Aging test )	Temperature : 125 ± 2 °C Duration : 168 hours	MIL-STD 202G method 108A
Cold resistance	Temperature : -40 ± 2 °C Duration : 96 hours	IEC 60068-2-1



**CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

**NOTES:**

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.